GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
RAJYA SABHA
UNSTARRED QUESTION NO. 2286
TO BE ANSWERED ON: 19.12.2025

PROPOSAL FOR LAUNCH OF ISM 2.0

2286. # DR. KALPANA SAINI:
SHRI MAYANKKUMAR NAYAK:
SHRI AMAR PAL MAURYA:
SHRI KESRIDEVSINH JHALA:
SHRI NARAYANA KORAGAPPA:
SHRI GHANSHYAM TIWARI:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

(a) achievements especially in fabrication, assembly and packaging under India Semiconductor Mission (ISM) 1.0 since inception;
(b) whether Government proposes to launch ISM 2.0, if so, expected timeline for its announcement and implementation;
(c) estimated financial allocation and strategic priorities being considered under ISM 2.0 to strengthen India's position in global semiconductor value chain;
(d) whether Government has any plan to attract companies to invent and engage in advanced lithography, semiconductor equipment manufacturing and allied technology ecosystems to set up operations in the country; and
(e) if so, the details thereof along with long-term goal of semiconductor self-reliance in India?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (e)**:** The semiconductor development strategy is inspired by Hon'ble Prime Minister's vision of Atmanirbhar Bharat and Make in India, Make for the World.

As a part of this strategy and given the foundational nature of semiconductor industry, Government is developing a complete ecosystem covering talentpool, design, fabrication, assembly, testing and packaging.

'Semicon India Programme' has been launched as part of this strategy.

In less than 3 years, ten units (2 fabs and 8 ATMP/OSATs) have been approved with cumulative investment of 1.6 Lakh Cr. These units include silicon fab, Silicon Carbide fab, advanced packaging, memory packaging, etc.

These will cater to chip requirements of sectors such as consumer appliances, industrial electronics, automobiles, telecommunications, aerospace, and power electronics etc.

Pilot facilities of 3 units approved under the Semicon India Programme are already operational.

Further, under DLI, 24 chip design projects are supported through startups, representing Rs 920 crore in project value. 94 companies have been provided free access to EDA tools for designing the chips enabling over 47 lakh hours of design tool usage.

In addition to the above, Government has also launched Chips to Start-ups program (C2S) programme with the objective to develop 85 thousand skilled manpower in the semiconductor sector.

The ChipIN Centre has been established at C-DAC Bangalore as a centralized national facility providing comprehensive chip-design and fabrication resources under the Design Linked Incentive (DLI) Scheme and Chips to Start-up (C2S) Programme.

Approximately, 1 lakh students from 300 organizations have been enrolled and 255 training sessions on design flow have been conducted in partnership with leading companies.

The entire ecosystem is being developed in India due to the Government policies. Companies involved in specialised gases, materials, components, warehousing, etc. are scaling up their operations in India. Companies involved in making tools for electronics and semiconductor manufacturing have also expanded their operations.

The Government of India continuously engages with all stakeholders, including industry, academia and other governments, to understand requirements and take further action as necessary.

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